

L Number	Hits	Search Text	DB	Time stamp
1	1395070	semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 14:20
2	12722	semiconductor and (metal adj wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 14:35
3	11	((semiconductor and (metal adj wiring)) and ((TiN or (titanium adj nitride)) with halogen)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 14:34
6	0	((semiconductor and (metal adj wiring)) and (copper with halogen with catalyst)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 14:33
7	2003	(semiconductor and (metal adj wiring)) and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 14:33
8	6	((semiconductor and (metal adj wiring)) and copper) and ((TiN or (titanium adj nitride)) with halogen)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 14:34
9	0	((semiconductor and (metal adj wiring)) and copper) and ((TiN or (titanium adj nitride)) with halogen with catalyst)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 14:40
10	0	((semiconductor and (metal adj wiring)) and copper) and ((TiN or (titanium adj nitride)) with halogen with catalys\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 14:35
11	0	semiconductor and (metal adj wiring) and (halogen with catalyst)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 14:36
12	5	(semiconductor and (metal adj wiring)) and (halogen with catalyst)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 14:36
13	0	((semiconductor and (metal adj wiring)) and copper) and (copper with halogen with catalyst)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 15:06
14	1	((semiconductor and (metal adj wiring)) and copper) and (halogen with catalyst)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 14:41

15	0	(semiconductor and (metal adj wiring)) and (copper with halogen with catalyst)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 16:08
16	27	semiconductor and (copper with halogen with catalyst)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 15:07
17	10	(semiconductor and (copper with halogen with catalyst)) and wir\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 15:07
18	33	(semiconductor and (metal adj wiring)) and copper and halogen and catalyst	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 16:12
19	3	(semiconductor and (metal adj wiring)) and copper and (halogen same catalyst)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 16:12

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1	69052	form\$4 with metal with wir\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:15
2	0	((form\$4 with metal with wir\$4) and (((titanium adj nitride) or TiN) with substrate with (halogen or iodine or I) with (adsorb\$4 adj (halogen or iodine)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:20
3	0	((form\$4 with metal with wir\$4) and (((titanium adj nitride) or TiN) same substrate same (halogen or iodine or I) same (adsorb\$4 adj (halogen or iodine)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:21
4	102	((form\$4 with metal with wir\$4) and (((titanium adj nitride) or TiN) same substrate same (halogen or iodine or I))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:42
5	0	((form\$4 with metal with wir\$4) and (((titanium adj nitride) or TiN) same substrate same (halogen or iodine or I))) and (adsorb\$4 adj (halogen or iodine))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:22
6	0	((form\$4 with metal with wir\$4) and (((titanium adj nitride) or TiN) same substrate same (halogen or iodine or I))) and (adsorb\$4 near3 (halogen or iodine))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:23
7	0	((form\$4 with metal with wir\$4) and (((titanium adj nitride) or TiN) same substrate same (halogen or iodine or I))) and (absorb\$4 near3 (halogen or iodine))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:23
9	7	((form\$4 with metal with wir\$4) and (((titanium adj nitride) or TiN) same substrate same (halogen or iodine or I))) and adsorb\$4) and (halogen or iodine)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:28
10	8	("6297147") or ("6423201") or ("6342444") or ("6218734").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:29
8	7	((form\$4 with metal with wir\$4) and (((titanium adj nitride) or TiN) same substrate same (halogen or iodine or I))) and adsorb\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:33
11	24	((form\$4 with metal with wir\$4) and (((titanium adj nitride) or TiN) with substrate with (halogen or iodine or I))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:45
13	0	((form\$4 with metal with wir\$4) and (((titanium adj nitride) or TiN) with substrate with (halogen or iodine or I))) and ((adsorb\$4 or absorb\$4 or adher\$4) near4 halogen)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:46

14	1	((form\$4 with metal with wir\$4) and (((titanium adj nitride) or TiN) with substrate with (halogen or Iodine or I))) and ((adsorb\$4 or absorb\$4 or adher\$4) with halogen)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:47
12	14	((form\$4 with metal with wir\$4) and (((titanium adj nitride) or TiN) with substrate with (halogen or Iodine or I))) and (adsorb\$4 or absorb\$4 or adher\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:53
15	0	((form\$4 with metal with wir\$4) and (((titanium adj nitride) or TiN) with substrate with (halogen or Iodine or I))) and (adsorb\$4 or absorb\$4 or adher\$4)) and (halogen with catalyst)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:53